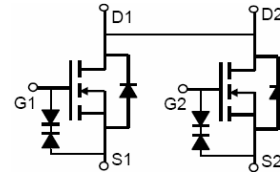


N-Channel Enhancement Mode Power MOSFET

Description

The FNK0203EA uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V. This device is suitable for use as a load switch or in PWM applications. It is ESD protected.



Schematic diagram

General Features

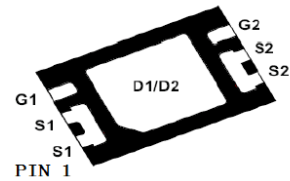
- $V_{DS} = 20V, I_D = 10A$
- $R_{DS(ON)} < 19m\Omega @ V_{GS}=2.5V$
- $R_{DS(ON)} < 13m\Omega @ V_{GS}=4.5V$
- ESD Rating: 2500V HBM
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- Uni-directional load switch
- Bi-directional load switch



Marking and pin assignment



DFN2*3-6 top view

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	8	A
Drain Current-Pulsed ^(Note 1)	I_{DM}	30	A
Maximum Power Dissipation	P_D	2	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient ^(Note 2)	$R_{\theta JA}$	62.5	$^\circ C/W$
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Electrical Characteristics ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$	-	-	1	μA

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	± 10	μA
On Characteristics <small>(Note 3)</small>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.45	0.7	1.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=4.5V, I_D=5A$	-	11	15	$m\Omega$
		$V_{GS}=2.5V, I_D=4A$	-	15	19	$m\Omega$
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_D=5A$	-	15	-	S
Dynamic Characteristics <small>(Note4)</small>						
Input Capacitance	C_{iss}	$V_{DS}=10V, V_{GS}=0V,$ $F=1.0MHz$	-	1800	-	PF
Output Capacitance	C_{oss}		-	230	-	PF
Reverse Transfer Capacitance	C_{rss}		-	200	-	PF
Switching Characteristics <small>(Note 4)</small>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=10V, R_L=1.2\Omega$ $V_{GS}=10V, R_{GEN}=3\Omega$	-	2.5	-	nS
Turn-on Rise Time	t_r		-	7.2	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	49	-	nS
Turn-Off Fall Time	t_f		-	10.8	-	nS
Total Gate Charge	Q_g	$V_{DS}=10V, I_D=8A,$ $V_{GS}=4.5V$	-	17.9	-	nC
Gate-Source Charge	Q_{gs}		-	1.5	-	nC
Gate-Drain Charge	Q_{gd}		-	4.7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <small>(Note 3)</small>	V_{SD}	$V_{GS}=0V, I_S=8A$	-	-	1.2	V
Diode Forward Current <small>(Note 2)</small>	I_S		-	-	8	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics

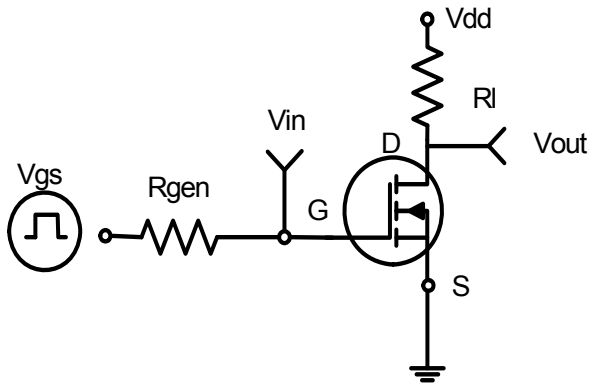


Figure 1: Switching Test Circuit



Figure 2: Switching Waveforms

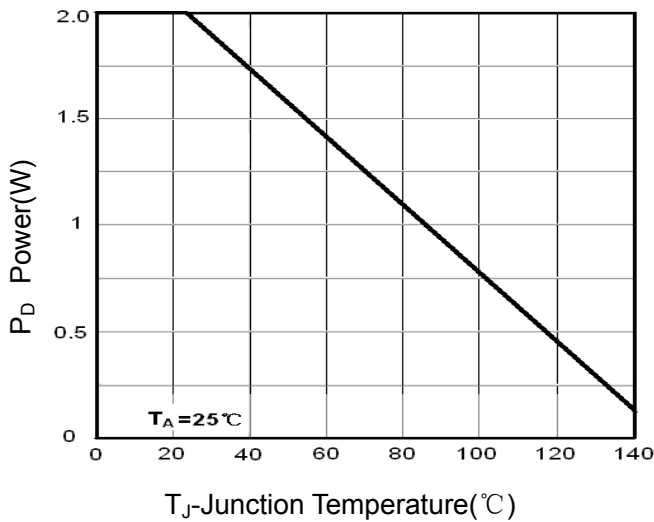


Figure 3 Power Dissipation

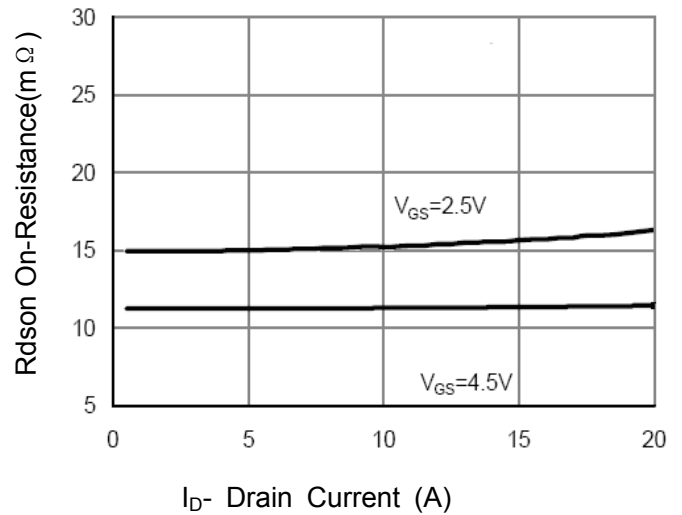


Figure 6 Drain-Source On-Resistance

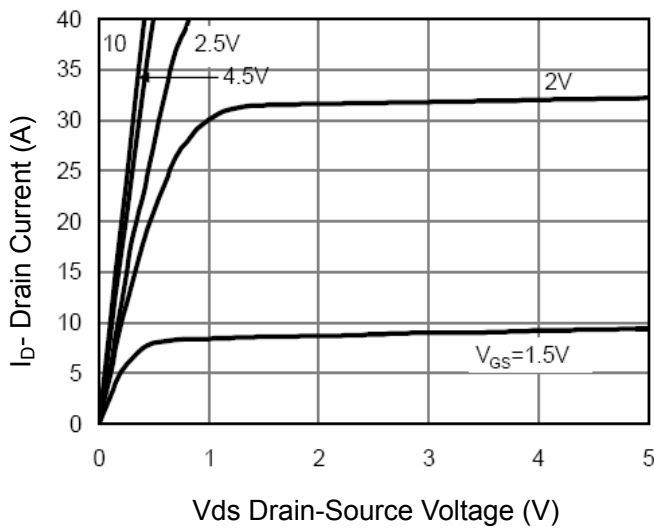


Figure 5 Output Characteristics

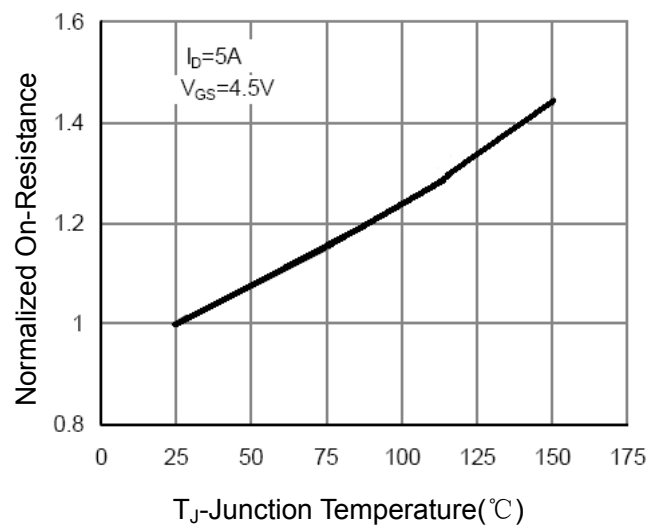


Figure 8 Drain-Source On-Resistance

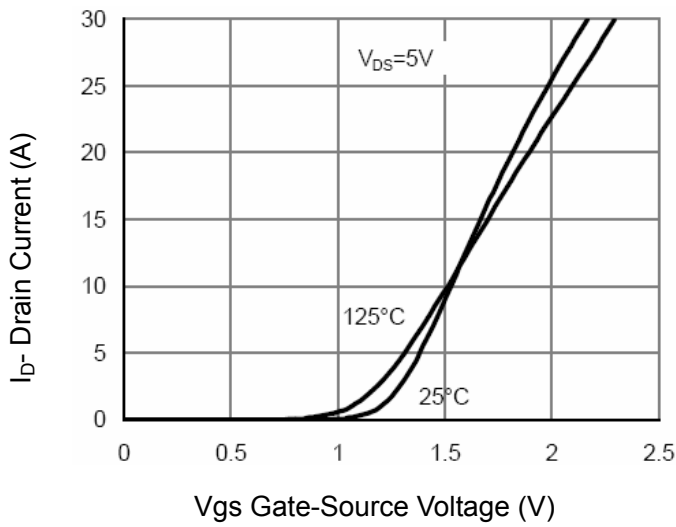


Figure 7 Transfer Characteristics

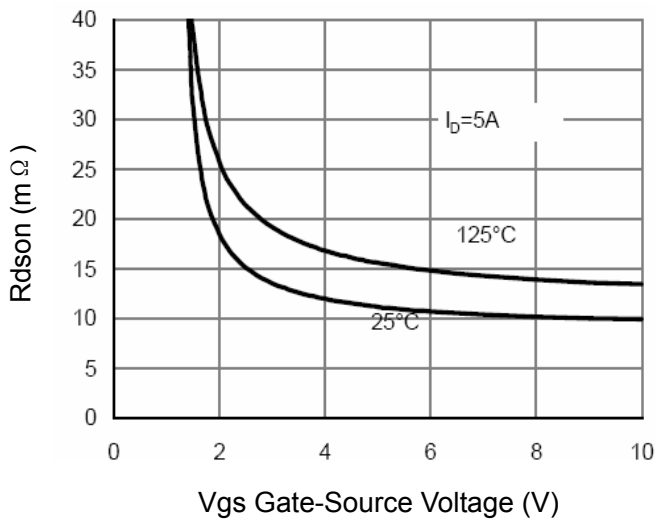


Figure 9 Rdson vs Vgs

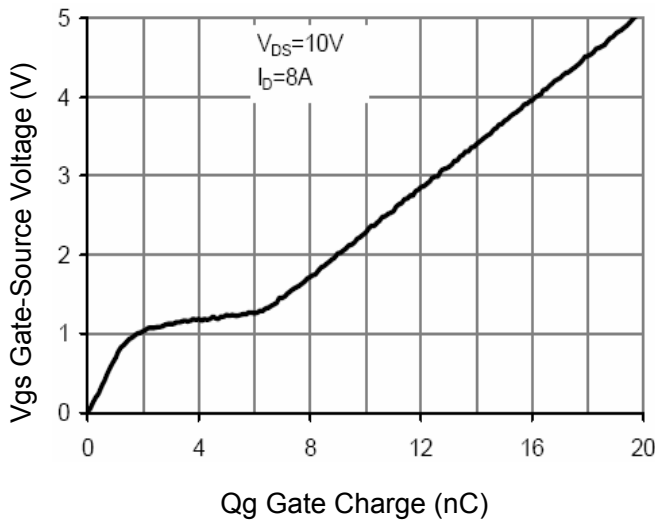


Figure 11 Gate Charge

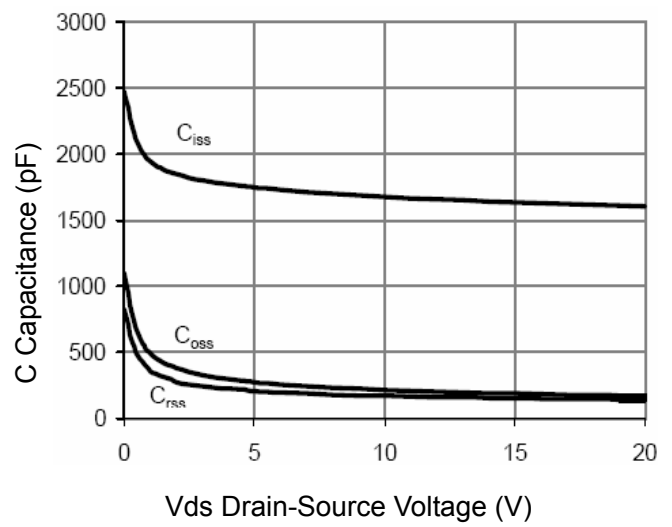


Figure 8 Capacitance vs Vds

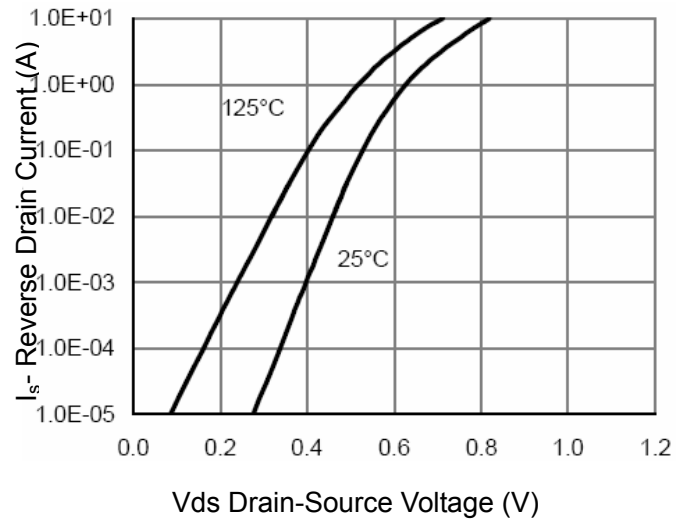


Figure 10 Source-Drain Diode Forward

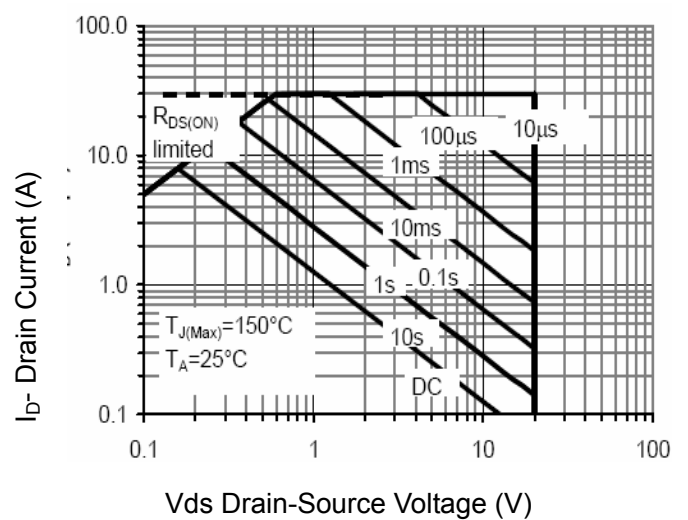


Figure 13 Safe Operation Area

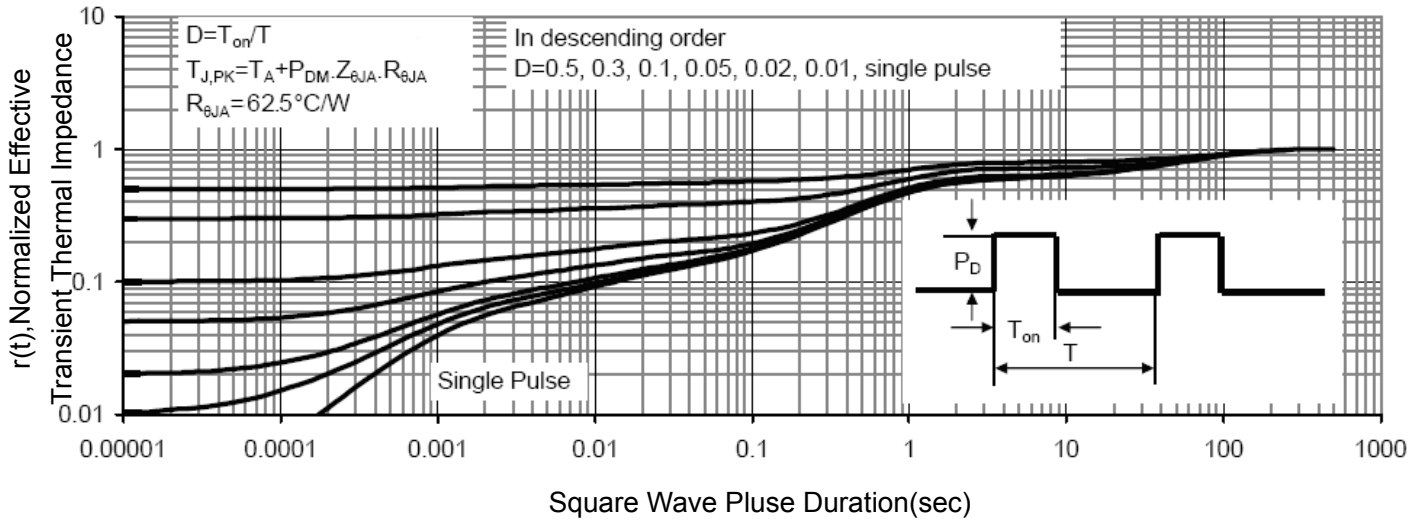


Figure 14 Normalized Maximum Transient Thermal Impedance

封装外形尺寸图

符号	单位: mm		
	MIN	NOM	MAX
A	1.95	2.00	2.05
B	2.95	3.00	3.05
C	1.45	1.50	1.55
D	1.65	1.70	1.75
E	0.33	0.38	0.43
F	0.25	0.30	0.35
G	0.20	0.25	0.30
H	0.35	0.40	0.45
I	0.2 BSC		
J	0.75	0.80	0.85
J1	0-0.05		
K	0.3×45° BSC		
L	0.5 BSC		
M	0.70	0.75	0.80
N	0.10	0.15	0.20

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